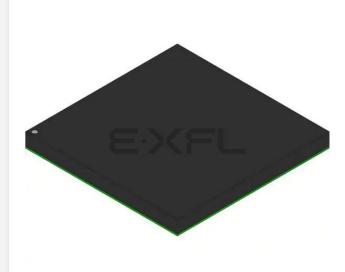
E·XFL

Altera - EP20K600EFC33-2X Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Detai	ls

Details	
Product Status	Active
Number of LABs/CLBs	2432
Number of Logic Elements/Cells	24320
Total RAM Bits	311296
Number of I/O	588
Number of Gates	1537000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-FBGA (33x33)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=ep20k600efc33-2x

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Flexible clock management circuitry with up to four phase-locked loops (PLLs)
 - Built-in low-skew clock tree
 - Up to eight global clock signals
 - ClockLock[®] feature reducing clock delay and skew
 - ClockBoost[®] feature providing clock multiplication and division
 - ClockShiftTM programmable clock phase and delay shifting
- Powerful I/O features
 - Compliant with peripheral component interconnect Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2* for 3.3-V operation at 33 or 66 MHz and 32 or 64 bits
 - Support for high-speed external memories, including DDR SDRAM and ZBT SRAM (ZBT is a trademark of Integrated Device Technology, Inc.)
 - Bidirectional I/O performance $(t_{CO} + t_{SU})$ up to 250 MHz
 - LVDS performance up to 840 Mbits per channel
 - Direct connection from I/O pins to local interconnect providing fast t_{CO} and t_{SU} times for complex logic
 - MultiVolt I/O interface support to interface with 1.8-V, 2.5-V, 3.3-V, and 5.0-V devices (see Table 3)
 - Programmable clamp to V_{CCIO}
 - Individual tri-state output enable control for each pin
 - Programmable output slew-rate control to reduce switching noise
 - Support for advanced I/O standards, including low-voltage differential signaling (LVDS), LVPECL, PCI-X, AGP, CTT, stubseries terminated logic (SSTL-3 and SSTL-2), Gunning transceiver logic plus (GTL+), and high-speed terminated logic (HSTL Class I)
 - Pull-up on I/O pins before and during configuration
- Advanced interconnect structure
 - Four-level hierarchical FastTrack[®] Interconnect structure providing fast, predictable interconnect delays
 - Dedicated carry chain that implements arithmetic functions such as fast adders, counters, and comparators (automatically used by software tools and megafunctions)
 - Dedicated cascade chain that implements high-speed, high-fan-in logic functions (automatically used by software tools and megafunctions)
 - Interleaved local interconnect allows one LE to drive 29 other LEs through the fast local interconnect
- Advanced packaging options
 - Available in a variety of packages with 144 to 1,020 pins (see Tables 4 through 7)
 - FineLine BGA[®] packages maximize board space efficiency
- Advanced software support
 - Software design support and automatic place-and-route provided by the Altera[®] Quartus[®] II development system for

Each LAB contains dedicated logic for driving control signals to its LEs and ESBs. The control signals include clock, clock enable, asynchronous clear, asynchronous preset, asynchronous load, synchronous clear, and synchronous load signals. A maximum of six control signals can be used at a time. Although synchronous load and clear signals are generally used when implementing counters, they can also be used with other functions.

Each LAB can use two clocks and two clock enable signals. Each LAB's clock and clock enable signals are linked (e.g., any LE in a particular LAB using CLK1 will also use CLKENA1). LEs with the same clock but different clock enable signals either use both clock signals in one LAB or are placed into separate LABs.

If both the rising and falling edges of a clock are used in a LAB, both LABwide clock signals are used.

The LAB-wide control signals can be generated from the LAB local interconnect, global signals, and dedicated clock pins. The inherent low skew of the FastTrack Interconnect enables it to be used for clock distribution. Figure 4 shows the LAB control signal generation circuit.

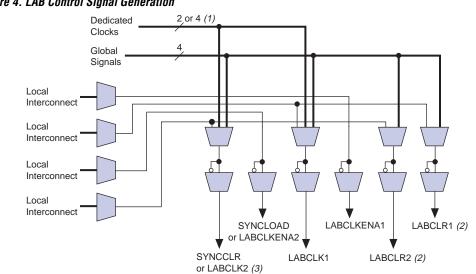


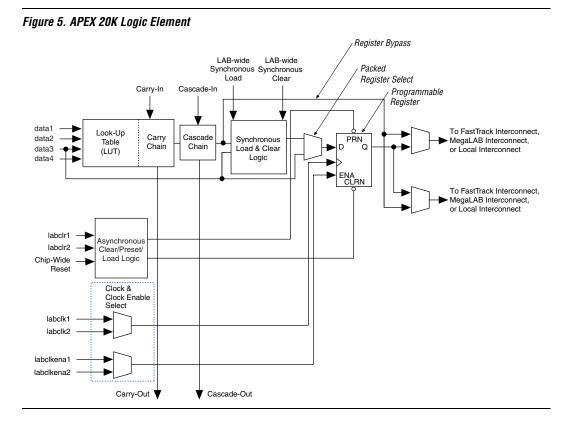
Figure 4. LAB Control Signal Generation

Notes to Figure 4:

- APEX 20KE devices have four dedicated clocks. (1)
- The LABCLR1 and LABCLR2 signals also control asynchronous load and asynchronous preset for LEs within the (2) LAB.
- (3)The SYNCCLR signal can be generated by the local interconnect or global signals.

Logic Element

The LE, the smallest unit of logic in the APEX 20K architecture, is compact and provides efficient logic usage. Each LE contains a four-input LUT, which is a function generator that can quickly implement any function of four variables. In addition, each LE contains a programmable register and carry and cascade chains. Each LE drives the local interconnect, MegaLAB interconnect, and FastTrack Interconnect routing structures. See Figure 5.



Each LE's programmable register can be configured for D, T, JK, or SR operation. The register's clock and clear control signals can be driven by global signals, general-purpose I/O pins, or any internal logic. For combinatorial functions, the register is bypassed and the output of the LUT drives the outputs of the LE.

Each LE has two outputs that drive the local, MegaLAB, or FastTrack Interconnect routing structure. Each output can be driven independently by the LUT's or register's output. For example, the LUT can drive one output while the register drives the other output. This feature, called register packing, improves device utilization because the register and the LUT can be used for unrelated functions. The LE can also drive out registered and unregistered versions of the LUT output.

The APEX 20K architecture provides two types of dedicated high-speed data paths that connect adjacent LEs without using local interconnect paths: carry chains and cascade chains. A carry chain supports high-speed arithmetic functions such as counters and adders, while a cascade chain implements wide-input functions such as equality comparators with minimum delay. Carry and cascade chains connect LEs 1 through 10 in an LAB and all LABs in the same MegaLAB structure.

Carry Chain

The carry chain provides a very fast carry-forward function between LEs. The carry-in signal from a lower-order bit drives forward into the higherorder bit via the carry chain, and feeds into both the LUT and the next portion of the carry chain. This feature allows the APEX 20K architecture to implement high-speed counters, adders, and comparators of arbitrary width. Carry chain logic can be created automatically by the Quartus II software Compiler during design processing, or manually by the designer during design entry. Parameterized functions such as library of parameterized modules (LPM) and DesignWare functions automatically take advantage of carry chains for the appropriate functions.

The Quartus II software Compiler creates carry chains longer than ten LEs by linking LABs together automatically. For enhanced fitting, a long carry chain skips alternate LABs in a MegaLAB[™] structure. A carry chain longer than one LAB skips either from an even-numbered LAB to the next even-numbered LAB, or from an odd-numbered LAB to the next odd-numbered LAB. For example, the last LE of the first LAB in the upper-left MegaLAB structure carries to the first LE of the third LAB in the MegaLAB structure.

Figure 6 shows how an *n*-bit full adder can be implemented in n + 1 LEs with the carry chain. One portion of the LUT generates the sum of two bits using the input signals and the carry-in signal; the sum is routed to the output of the LE. The register can be bypassed for simple adders or used for accumulator functions. Another portion of the LUT and the carry chain logic generates the carry-out signal, which is routed directly to the carry-in signal of the next-higher-order bit. The final carry-out signal is routed to an LE, where it is driven onto the local, MegaLAB, or FastTrack Interconnect routing structures.

Normal Mode

The normal mode is suitable for general logic applications, combinatorial functions, or wide decoding functions that can take advantage of a cascade chain. In normal mode, four data inputs from the LAB local interconnect and the carry-in are inputs to a four-input LUT. The Quartus II software Compiler automatically selects the carry-in or the DATA3 signal as one of the inputs to the LUT. The LUT output can be combined with the cascade-in signal to form a cascade chain through the cascade-out signal. LEs in normal mode support packed registers.

Arithmetic Mode

The arithmetic mode is ideal for implementing adders, accumulators, and comparators. An LE in arithmetic mode uses two 3-input LUTs. One LUT computes a three-input function; the other generates a carry output. As shown in Figure 8, the first LUT uses the carry-in signal and two data inputs from the LAB local interconnect to generate a combinatorial or registered output. For example, when implementing an adder, this output is the sum of three signals: DATA1, DATA2, and carry-in. The second LUT uses the same three signals to generate a carry-out signal, thereby creating a carry chain. The arithmetic mode also supports simultaneous use of the cascade chain. LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output.

The Quartus II software implements parameterized functions that use the arithmetic mode automatically where appropriate; the designer does not need to specify how the carry chain will be used.

Counter Mode

The counter mode offers clock enable, counter enable, synchronous up/down control, synchronous clear, and synchronous load options. The counter enable and synchronous up/down control signals are generated from the data inputs of the LAB local interconnect. The synchronous clear and synchronous load options are LAB-wide signals that affect all registers in the LAB. Consequently, if any of the LEs in an LAB use the counter mode, other LEs in that LAB must be used as part of the same counter or be used for a combinatorial function. The Quartus II software automatically places any registers that are not used by the counter into other LABs.

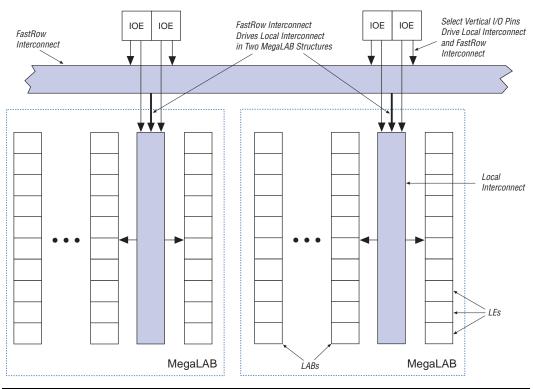


Figure 12. APEX 20KE FastRow Interconnect

Table 9 summarizes how various elements of the APEX 20K architecture drive each other.

Table 9. AP	EX 20K	Routing S	cheme						
Source	Destination								
	Row I/O Pin	Column I/O Pin	LE	ESB	Local Interconnect	MegaLAB Interconnect	Row FastTrack Interconnect	Column FastTrack Interconnect	FastRow Interconnect
Row I/O Pin					✓	\checkmark	\checkmark	✓	
Column I/O Pin								~	✓ (1)
LE					\checkmark	\checkmark	\checkmark	\checkmark	
ESB					 Image: A set of the set of the	\checkmark	~	~	
Local Interconnect	~	~	~	~					
MegaLAB Interconnect					~				
Row FastTrack Interconnect						~		~	
Column FastTrack Interconnect						~	~		
FastRow Interconnect					✓ (1)				

Note to Table 9:

(1) This connection is supported in APEX 20KE devices only.

Product-Term Logic

The product-term portion of the MultiCore architecture is implemented with the ESB. The ESB can be configured to act as a block of macrocells on an ESB-by-ESB basis. Each ESB is fed by 32 inputs from the adjacent local interconnect; therefore, it can be driven by the MegaLAB interconnect or the adjacent LAB. Also, nine ESB macrocells feed back into the ESB through the local interconnect for higher performance. Dedicated clock pins, global signals, and additional inputs from the local interconnect drive the ESB control signals.

In product-term mode, each ESB contains 16 macrocells. Each macrocell consists of two product terms and a programmable register. Figure 13 shows the ESB in product-term mode.

Advanced I/O Standard Support

APEX 20KE IOEs support the following I/O standards: LVTTL, LVCMOS, 1.8-V I/O, 2.5-V I/O, 3.3-V PCI, PCI-X, 3.3-V AGP, LVDS, LVPECL, GTL+, CTT, HSTL Class I, SSTL-3 Class I and II, and SSTL-2 Class I and II.



For more information on I/O standards supported by APEX 20KE devices, see *Application Note* 117 (*Using Selectable I/O Standards in Altera Devices*).

The APEX 20KE device contains eight I/O banks. In QFP packages, the banks are linked to form four I/O banks. The I/O banks directly support all standards except LVDS and LVPECL. All I/O banks can support LVDS and LVPECL with the addition of external resistors. In addition, one block within a bank contains circuitry to support high-speed True-LVDS and LVPECL inputs, and another block within a particular bank supports high-speed True-LVDS and LVPECL outputs. The LVDS blocks support all of the I/O standards. Each I/O bank has its own VCCIO pins. A single device can support 1.8-V, 2.5-V, and 3.3-V interfaces; each bank can support a different standard independently. Each bank can also use a separate V_{REF} level so that each bank can support any of the terminated standards (such as SSTL-3) independently. Within a bank, any one of the terminated standards can be supported. EP20K300E and larger APEX 20KE devices support the LVDS interface for data pins (smaller devices support LVDS clock pins, but not data pins). All EP20K300E and larger devices support the LVDS interface for data pins up to 155 Mbit per channel; EP20K400E devices and larger with an X-suffix on the ordering code add a serializer/deserializer circuit and PLL for higher-speed support.

Each bank can support multiple standards with the same VCCIO for output pins. Each bank can support one voltage-referenced I/O standard, but it can support multiple I/O standards with the same VCCIO voltage level. For example, when VCCIO is 3.3 V, a bank can support LVTTL, LVCMOS, 3.3-V PCI, and SSTL-3 for inputs and outputs.

When the LVDS banks are not used as LVDS I/O banks, they support all of the other I/O standards. Figure 29 shows the arrangement of the APEX 20KE I/O banks.



Figure 29. APEX 20KE I/O Banks

Notes to Figure 29:

- For more information on placing I/O pins in LVDS blocks, refer to the Guidelines for Using LVDS Blocks section in Application Note 120 (Using LVDS in APEX 20KE Devices).
- (2) If the LVDS input and output blocks are not used for LVDS, they can support all of the I/O standards and can be used as input, output, or bidirectional pins with V_{CCIO} set to 3.3 V, 2.5 V, or 1.8 V.

Power Sequencing & Hot Socketing

Because APEX 20K and APEX 20KE devices can be used in a mixedvoltage environment, they have been designed specifically to tolerate any possible power-up sequence. Therefore, the V_{CCIO} and V_{CCINT} power supplies may be powered in any order.

For more information, please refer to the "Power Sequencing Considerations" section in the *Configuring APEX 20KE & APEX 20KC Devices* chapter of the *Configuration Devices Handbook*.

Signals can be driven into APEX 20K devices before and during power-up without damaging the device. In addition, APEX 20K devices do not drive out during power-up. Once operating conditions are reached and the device is configured, APEX 20K and APEX 20KE devices operate as specified by the user.

For designs that require both a multiplied and non-multiplied clock, the clock trace on the board can be connected to CLK2p. Table 14 shows the combinations supported by the ClockLock and ClockBoost circuitry. The CLK2p pin can feed both the ClockLock and ClockBoost circuitry in the APEX 20K device. However, when both circuits are used, the other clock pin (CLK1p) cannot be used.

Table 14. Multiplication Factor Combinations					
Clock 1 Clock 2					
x1 x1					
×1, ×2 ×2					
×1, ×2, ×4 ×4					

APEX 20KE ClockLock Feature

APEX 20KE devices include an enhanced ClockLock feature set. These devices include up to four PLLs, which can be used independently. Two PLLs are designed for either general-purpose use or LVDS use (on devices that support LVDS I/O pins). The remaining two PLLs are designed for general-purpose use. The EP20K200E and smaller devices have two PLLs; the EP20K300E and larger devices have four PLLs.

The following sections describe some of the features offered by the APEX 20KE PLLs.

External PLL Feedback

The ClockLock circuit's output can be driven off-chip to clock other devices in the system; further, the feedback loop of the PLL can be routed off-chip. This feature allows the designer to exercise fine control over the I/O interface between the APEX 20KE device and another high-speed device, such as SDRAM.

Clock Multiplication

The APEX 20KE ClockBoost circuit can multiply or divide clocks by a programmable number. The clock can be multiplied by $m/(n \times k)$ or $m/(n \times v)$, where *m* and *k* range from 2 to 160, and *n* and *v* range from 1 to 16. Clock multiplication and division can be used for time-domain multiplexing and other functions, which can reduce design LE requirements.

Device		IDCODE (32 Bits) (1)							
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer Identity (11 Bits)	1 (1 Bit) (2)					
EP20K30E	0000	1000 0000 0011 0000	000 0110 1110	1					
EP20K60E	0000	1000 0000 0110 0000	000 0110 1110	1					
EP20K100	0000	0000 0100 0001 0110	000 0110 1110	1					
EP20K100E	0000	1000 0001 0000 0000	000 0110 1110	1					
EP20K160E	0000	1000 0001 0110 0000	000 0110 1110	1					
EP20K200	0000	0000 1000 0011 0010	000 0110 1110	1					
EP20K200E	0000	1000 0010 0000 0000	000 0110 1110	1					
EP20K300E	0000	1000 0011 0000 0000	000 0110 1110	1					
EP20K400	0000	0001 0110 0110 0100	000 0110 1110	1					
EP20K400E	0000	1000 0100 0000 0000	000 0110 1110	1					
EP20K600E	0000	1000 0110 0000 0000	000 0110 1110	1					
EP20K1000E	0000	1001 0000 0000 0000	000 0110 1110	1					

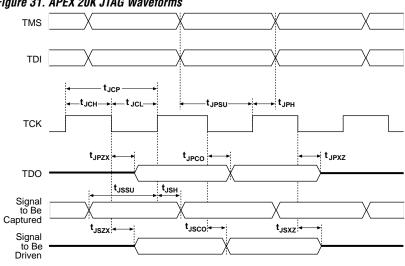
11- 04 00 04 4 ~

Notes to Table 21:

The most significant bit (MSB) is on the left. (1)

(2) The IDCODE's least significant bit (LSB) is always 1.

Figure 31 shows the timing requirements for the JTAG signals.





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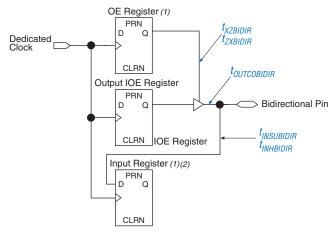


Figure 40. Synchronous Bidirectional Pin External Timing

Notes to Figure 40:

- (1) The output enable and input registers are LE registers in the LAB adjacent to a bidirectional row pin. The output enable register is set with "Output Enable Routing= Signal-Pin" option in the Quartus II software.
- (2) The LAB adjacent input register is set with "Decrease Input Delay to Internal Cells= Off". This maintains a zero hold time for lab adjacent registers while giving a fast, position independent setup time. A faster setup time with zero hold time is possible by setting "Decrease Input Delay to Internal Cells= ON" and moving the input register farther away from the bidirectional pin. The exact position where zero hold occurs with the minimum setup time, varies with device density and speed grade.

Table 31 describes the f_{MAX} timing parameters shown in Figure 36 on page 68.

Table 31. APEX 20K f _{MAX} Timing Parameters (Part 1 of 2)					
Symbol	Parameter				
t _{SU}	LE register setup time before clock				
t _H	LE register hold time after clock				
t _{CO}	LE register clock-to-output delay				
t _{LUT}	LUT delay for data-in				
t _{ESBRC}	ESB Asynchronous read cycle time				
t _{ESBWC}	ESB Asynchronous write cycle time				
t _{ESBWESU}	ESB WE setup time before clock when using input register				
t _{ESBDATASU}	ESB data setup time before clock when using input register				
t _{ESBDATAH}	ESB data hold time after clock when using input register				
t _{ESBADDRSU}	ESB address setup time before clock when using input registers				
t _{ESBDATACO1}	ESB clock-to-output delay when using output registers				

Note to Tables 32 and 33:

(1) These timing parameters are sample-tested only.

Tables 34 through 37 show APEX 20KE LE, ESB, routing, and functional timing microparameters for the f_{MAX} timing model.

Table 34. APEX 20KE LE Timing Microparameters				
Symbol	Parameter			
t _{SU}	LE register setup time before clock			
t _H	LE register hold time after clock			
t _{CO}	LE register clock-to-output delay			
t _{LUT}	LUT delay for data-in to data-out			

Table 35. APEX 20KE ESB Timing Microparameters					
Symbol	Parameter				
t _{ESBARC}	ESB Asynchronous read cycle time				
t _{ESBSRC}	ESB Synchronous read cycle time				
t _{ESBAWC}	ESB Asynchronous write cycle time				
t _{ESBSWC}	ESB Synchronous write cycle time				
t _{ESBWASU}	ESB write address setup time with respect to WE				
t _{ESBWAH}	ESB write address hold time with respect to WE				
t _{ESBWDSU}	ESB data setup time with respect to WE				
t _{ESBWDH}	ESB data hold time with respect to WE				
t _{ESBRASU}	ESB read address setup time with respect to RE				
t _{ESBRAH}	ESB read address hold time with respect to RE				
t _{ESBWESU}	ESB WE setup time before clock when using input register				
t _{ESBWEH}	ESB WE hold time after clock when using input register				
t _{ESBDATASU}	ESB data setup time before clock when using input register				
t _{ESBDATAH}	ESB data hold time after clock when using input register				
^t ESBWADDRSU	ESB write address setup time before clock when using input registers				
t _{ESBRADDRSU}	ESB read address setup time before clock when using input registers				
t _{ESBDATACO1}	ESB clock-to-output delay when using output registers				
t _{ESBDATACO2}	ESB clock-to-output delay without output registers				
t _{ESBDD}	ESB data-in to data-out delay for RAM mode				
t _{PD}	ESB Macrocell input to non-registered output				
t _{PTERMSU}	ESB Macrocell register setup time before clock				
t _{PTERMCO}	ESB Macrocell register clock-to-output delay				

Table 36. APEX 20KE Routing Timing Microparameters Note (1)					
Symbol	Parameter				
t _{F1-4}	Fanout delay using Local Interconnect				
t _{F5-20}	Fanout delay estimate using MegaLab Interconnect				
t _{F20+}	Fanout delay estimate using FastTrack Interconnect				

Note to Table 36:

 These parameters are worst-case values for typical applications. Post-compilation timing simulation and timing analysis are required to determine actual worst-case performance.

Table 37. APEX 20KE Functional Timing Microparameters				
Symbol	Parameter			
ТСН	Minimum clock high time from clock pin			
TCL	Minimum clock low time from clock pin			
TCLRP	LE clear Pulse Width			
TPREP	LE preset pulse width			
TESBCH	Clock high time for ESB			
TESBCL	Clock low time for ESB			
TESBWP	Write pulse width			
TESBRP	Read pulse width			

Table 37. APEX 20KE Functional Timing Microparameters

Tables 38 and 39 describe the APEX 20KE external timing parameters.

Table 38. APEX 20KE External Timing Parameters Note (1)						
Symbol	Clock Parameter Conditions					
t _{INSU}	Setup time with global clock at IOE input register					
t _{INH}	Hold time with global clock at IOE input register					
t _{оитсо}	Clock-to-output delay with global clock at IOE output register	C1 = 10 pF				
t _{INSUPLL}	Setup time with PLL clock at IOE input register					
t _{INHPLL}	Hold time with PLL clock at IOE input register					
t _{OUTCOPLL}	Clock-to-output delay with PLL clock at IOE output register	C1 = 10 pF				

Tables 40 through 42 show the f_{MAX} timing parameters for EP20K100, EP20K200, and EP20K400 APEX 20K devices.

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Units
	Min	Max	Min	Max	Min	Max	1
t _{SU}	0.5		0.6		0.8		ns
t _H	0.7		0.8		1.0		ns
t _{CO}		0.3		0.4		0.5	ns
t _{lut}		0.8		1.0		1.3	ns
t _{ESBRC}		1.7		2.1		2.4	ns
t _{ESBWC}		5.7		6.9		8.1	ns
t _{ESBWESU}	3.3		3.9		4.6		ns
t _{ESBDATASU}	2.2		2.7		3.1		ns
t _{ESBDATAH}	0.6		0.8		0.9		ns
t _{ESBADDRSU}	2.4		2.9		3.3		ns
t _{ESBDATACO1}		1.3		1.6		1.8	ns
t _{ESBDATACO2}		2.6		3.1		3.6	ns
t _{ESBDD}		2.5		3.3		3.6	ns
t _{PD}		2.5		3.0		3.6	ns
TERMSU	2.3		2.6		3.2		ns
t _{PTERMCO}		1.5		1.8		2.1	ns
t _{F1-4}		0.5		0.6		0.7	ns
t _{F5-20}		1.6		1.7		1.8	ns
t _{F20+}		2.2		2.2		2.3	ns
t _{CH}	2.0		2.5		3.0		ns
t _{CL}	2.0		2.5		3.0		ns
t _{CLRP}	0.3		0.4		0.4		ns
t _{PREP}	0.5		0.5		0.5		ns
t _{ESBCH}	2.0		2.5		3.0		ns
t _{ESBCL}	2.0		2.5		3.0		ns
t _{ESBWP}	1.6		1.9		2.2		ns
t _{ESBRP}	1.0		1.3		1.4		ns

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	1
t _{INSUBIDIR} (1)	1.9		2.3		2.6		ns
t _{INHBIDIR} (1)	0.0		0.0		0.0		ns
t _{OUTCOBIDIR} (1)	2.0	4.6	2.0	5.6	2.0	6.8	ns
t _{XZBIDIR} (1)		5.0		5.9		6.9	ns
t _{ZXBIDIR} (1)		5.0		5.9		6.9	ns
t _{INSUBIDIR} (2)	1.1		1.2		-		ns
t _{INHBIDIR} (2)	0.0		0.0		-		ns
t _{OUTCOBIDIR} (2)	0.5	2.7	0.5	3.1	-	-	ns
t _{XZBIDIR} (2)		4.3		5.0		-	ns
t _{ZXBIDIR} (2)		4.3		5.0		-	ns

Table 47. EP20K400 External Timing Parameters

Symbol	-1 Spee	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade					
	Min	Max	Min	Max	Min	Max					
t _{INSU} (1)	1.4		1.8		2.0		ns				
t _{INH} (1)	0.0		0.0		0.0		ns				
t _{OUTCO} (1)	2.0	4.9	2.0	6.1	2.0	7.0	ns				
t _{INSU} (2)	0.4		1.0		-		ns				
t _{INH} (2)	0.0		0.0		-		ns				
t _{оитсо} (2)	0.5	3.1	0.5	4.1	-	-	ns				

Table 48. EP20K400 External Bidirectional Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Мах	
t _{INSUBIDIR} (1)	1.4		1.8		2.0		ns
t _{INHBIDIR} (1)	0.0		0.0		0.0		ns
t _{OUTCOBIDIR} (1)	2.0	4.9	2.0	6.1	2.0	7.0	ns
t _{XZBIDIR} (1)		7.3		8.9		10.3	ns
t _{ZXBIDIR} (1)		7.3		8.9		10.3	ns
t _{INSUBIDIR} (2)	0.5		1.0		-		ns
t _{INHBIDIR} (2)	0.0		0.0		-		ns
t _{OUTCOBIDIR} (2)	0.5	3.1	0.5	4.1	-	-	ns
t _{XZBIDIR} (2)		6.2		7.6		-	ns
t _{ZXBIDIR} (2)		6.2		7.6		-	ns

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Tables 55 through 60 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K60E APEX 20KE devices.

Table 55. EP20K60E f _{MAX} LE Timing Microparameters										
Symbol	-	1		-2 -3			Unit			
	Min	Max	Min	Max	Min	Max	1			
t _{SU}	0.17		0.15		0.16		ns			
t _H	0.32		0.33		0.39		ns			
t _{CO}		0.29		0.40		0.60	ns			
t _{LUT}		0.77		1.07		1.59	ns			

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.65		2.02		2.11	ns
t _{ESBSRC}		2.21		2.70		3.11	ns
t _{ESBAWC}		3.04		3.79		4.42	ns
t _{ESBSWC}		2.81		3.56		4.10	ns
t _{ESBWASU}	0.54		0.66		0.73		ns
t _{ESBWAH}	0.36		0.45		0.47		ns
t _{ESBWDSU}	0.68		0.81		0.94		ns
t _{ESBWDH}	0.36		0.45		0.47		ns
t _{ESBRASU}	1.58		1.87		2.06		ns
t _{ESBRAH}	0.00		0.00		0.01		ns
t _{ESBWESU}	1.41		1.71		2.00		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	-0.02		-0.03		0.09		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.14		0.17		0.35		ns
t _{ESBRADDRSU}	0.21		0.27		0.43		ns
t _{ESBDATACO1}		1.04		1.30		1.46	ns
t _{ESBDATACO2}		2.15		2.70		3.16	ns
t _{ESBDD}		2.69		3.35		3.97	ns
t _{PD}		1.55		1.93		2.29	ns
t _{PTERMSU}	1.01		1.23		1.52		ns
t _{PTERMCO}		1.06		1.32		1.04	ns

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.78		2.02		1.95	ns
t _{ESBSRC}		2.52		2.91		3.14	ns
t _{ESBAWC}		3.52		4.11		4.40	ns
t _{ESBSWC}		3.23		3.84		4.16	ns
t _{ESBWASU}	0.62		0.67		0.61		ns
t _{ESBWAH}	0.41		0.55		0.55		ns
t _{ESBWDSU}	0.77		0.79		0.81		ns
t _{ESBWDH}	0.41		0.55		0.55		ns
t _{ESBRASU}	1.74		1.92		1.85		ns
t _{ESBRAH}	0.00		0.01		0.23		ns
t _{ESBWESU}	2.07		2.28		2.41		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	0.25		0.27		0.29		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.11		0.04		0.11		ns
t _{ESBRADDRSU}	0.14		0.11		0.16		ns
t _{ESBDATACO1}		1.29		1.50		1.63	ns
t _{ESBDATACO2}		2.55		2.99		3.22	ns
t _{ESBDD}		3.12		3.57		3.85	ns
t _{PD}		1.84		2.13		2.32	ns
t _{PTERMSU}	1.08		1.19		1.32		ns
t _{PTERMCO}		1.31		1.53		1.66	ns

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Symbol	-1 Speed Grade		-2 Spee	d Grade	-3 Spee	Unit	
	Min	Max	Min	Max	Min	Max	1
t _{insubidir}	3.22		3.33		3.51		ns
t _{inhbidir}	0.00		0.00		0.00		ns
toutcobidir	2.00	5.75	2.00	6.33	2.00	6.90	ns
t _{xzbidir}		6.31		7.09		7.76	ns
t _{ZXBIDIR}		6.31		7.09		7.76	ns
t _{insubidirpl} L	3.25		3.26				ns
t _{inhbidirpll}	0.00		0.00				ns
toutcobidirpll	0.50	2.25	0.50	2.99			ns
t _{xzbidirpll}		2.81		3.80			ns
t _{zxbidirpll}		2.81		3.80			ns

Tables 103 through 108 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K1500E APEX 20KE devices.

Table 103. EP20K1500E f _{MAX} LE Timing Microparameters								
Symbol	-1 Spee	d Grade	-2 Spee	-2 Speed Grade		d Grade	Unit	
	Min	Max	Min	Max	Min	Max		
t _{SU}	0.25		0.25		0.25		ns	
t _H	0.25		0.25		0.25		ns	
t _{CO}		0.28		0.32		0.33	ns	
t _{LUT}		0.80		0.95		1.13	ns	

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